

## **Vanishing Hysteresis in Carbon Nanotube Transistors Embedded in Boron Nitride / Polytetrafluoroethylene Heterolayers**

Sandeep Kumar,<sup>1,2</sup> Daghan Dagli,<sup>1,2</sup> Simone Dehm<sup>1</sup>, Chittaranjan Das,<sup>5</sup> Li Wei<sup>4</sup>, Yuan Chen<sup>4</sup>, Frank Hennrich<sup>3</sup>, and Ralph Krupke<sup>1,2,3</sup>

<sup>1</sup> Institute of Nanotechnology, Karlsruhe Institute of Technology, 76021 Karlsruhe, Germany

<sup>2</sup> Institute of Materials Science, Technische Universität Darmstadt, 76021 Karlsruhe, Germany

<sup>3</sup> Institute of Quantum Materials and Technology, Karlsruhe Institute of Technology, 76021 Karlsruhe, Germany

<sup>4</sup> School of Chemical and Biomolecular Engineering, The University of Sydney, NSW 2006, Australia

<sup>5</sup> Institute of Applied Materials, Karlsruhe Institute of Technology, 76021 Karlsruhe, Germany

### **Supplementary Material**

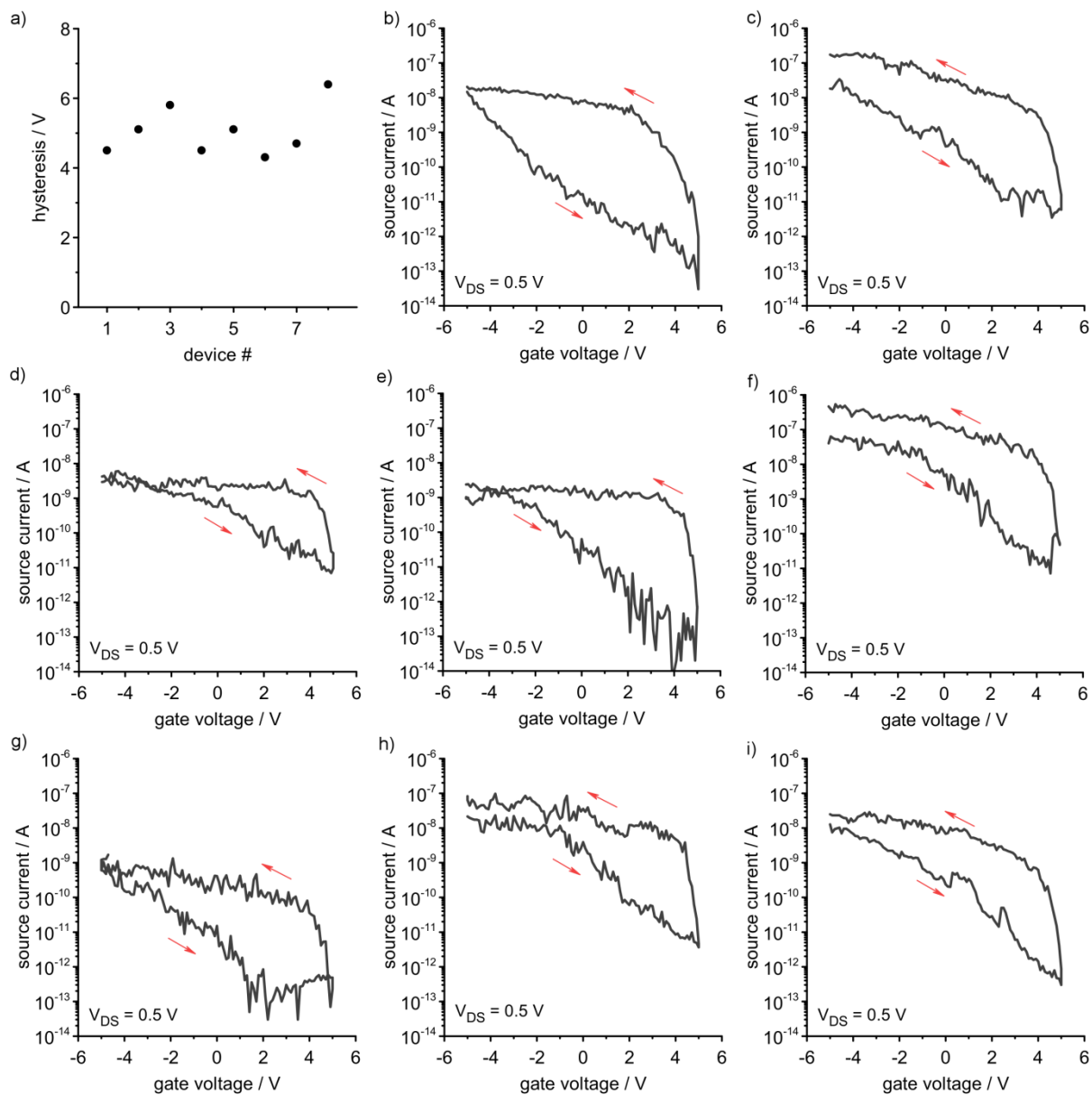
Figure S1: Characteristics of reference devices fabricated on Si/SiO<sub>2</sub> without h-BN and PTFE

Figure S2: Optical image of grown h-BN

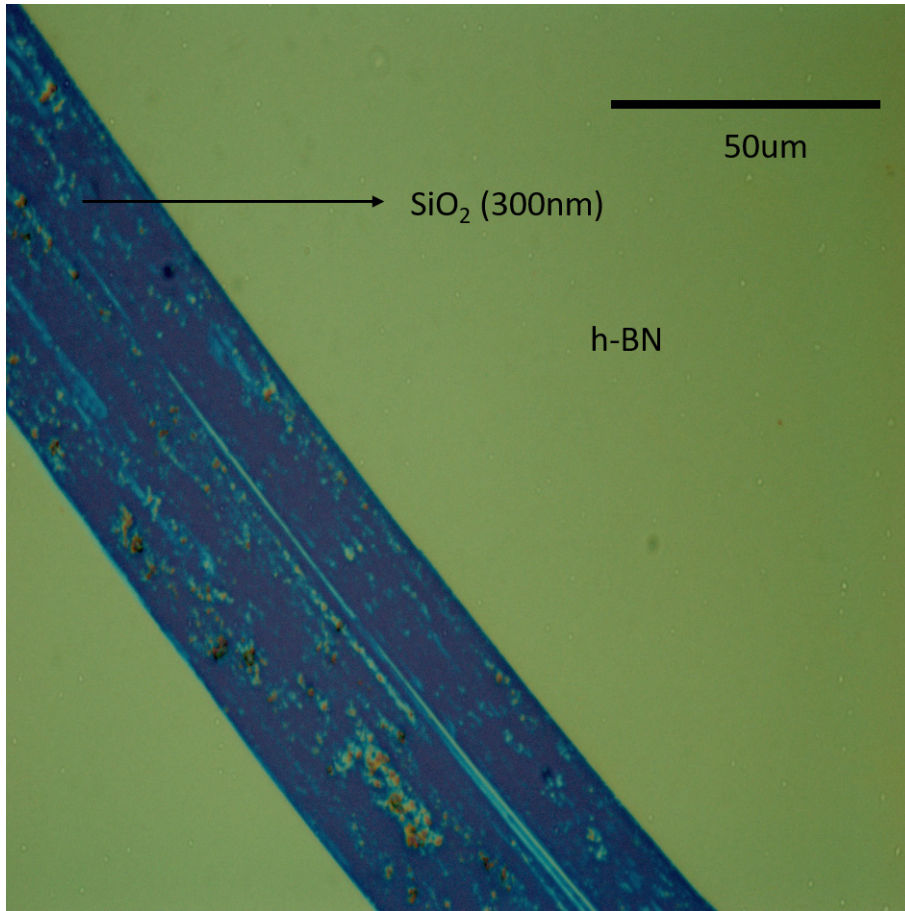
Figure S3: SEM images of grown h-BN

Table S1: Comparison of hysteresis in this work to previous literature for CNT transistors

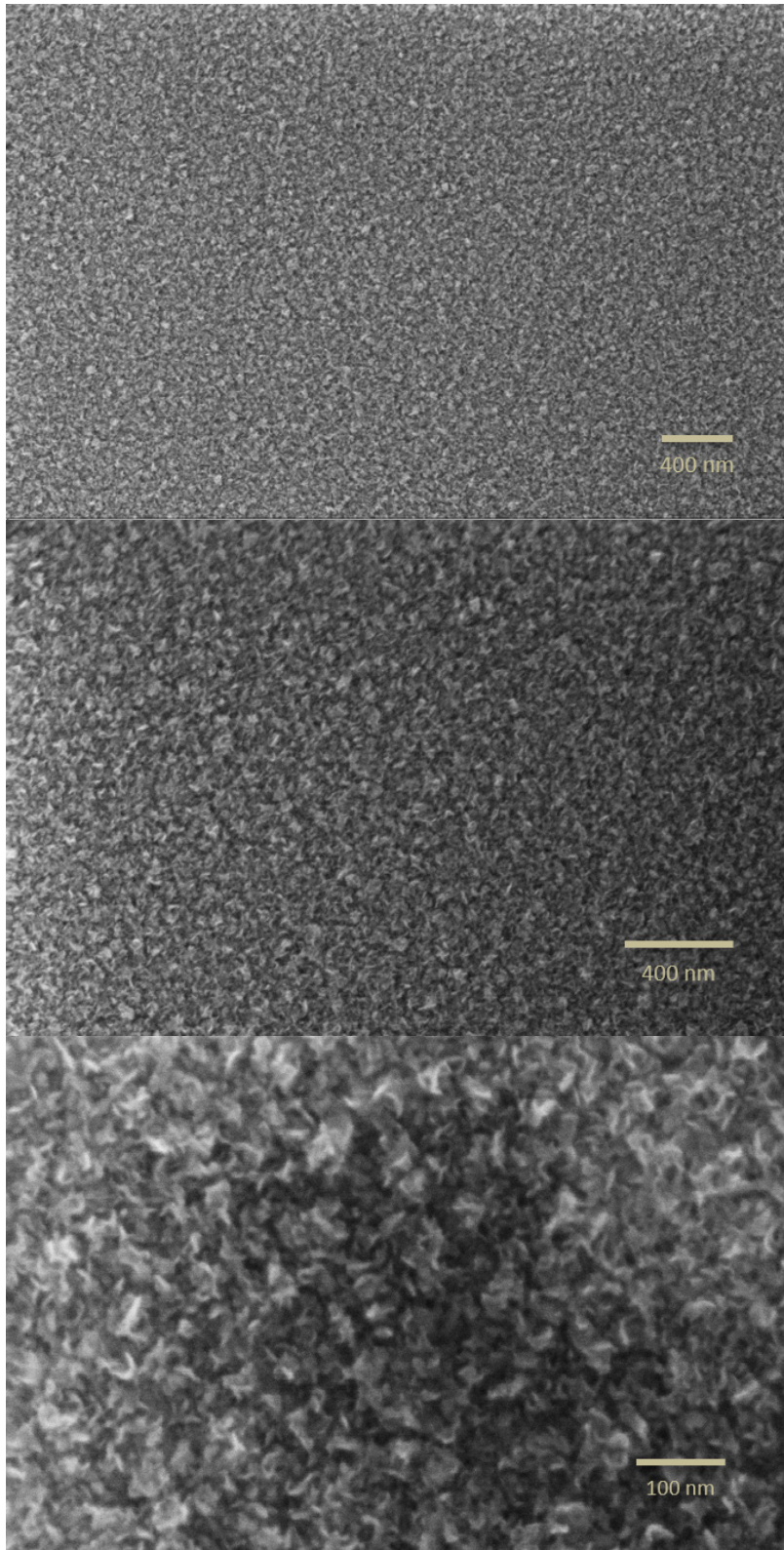
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**Figure S1:** (a) Hysteresis in transconductance curves for SWNCT devices on Si/SiO<sub>2</sub> without h-BN and PTFE encapsulation. (b-i) The corresponding transconductance curves were measured after vacuum annealing and are hence comparable to the h-BN supported devices prior Teflon coating.



**Figure S2:** Optical image of 80 nm thick h-BN grown on 300nm SiO<sub>2</sub>



**Figure S3:** SEM images of 80nm thick h-BN on 300nm h-BN at different magnifications.

Gate sweep window (Electric field)	Hysteresis in V	Dielectric thickness	Effective Dielectric constant	CNT Condition	DOI
-3 to 3 (3.14 MV/m)	2.2	SiO <sub>2</sub> -500nm Air-200nm	SiO <sub>2</sub> +air = 2.13	Suspended (CNT on top of electrodes)	10.1103/PhysRevB.86.115444 (ref 5)
-5 to 5 (2 MV/m)	<0.1	SiO <sub>2</sub> – 50nm	SiO <sub>2</sub> =3.9	PTFE encapsulation Dielectric Surface passivation (Electrodes on top of CNT film)	10.1021/am5013326 (ref 17)
-10 to 10 (16.7 MV/m)	5	SiO <sub>2</sub> -200nm Parylene-100nm	SiO <sub>2</sub> + Parylene (3.15) = 3.61	Hydrophobic film on dielectric (CNT on top of electrodes)	10.1002/adma.201004640 (ref 6)
-1 to 1 (16.7 MV/m)	0.1	SiO <sub>2</sub> -4nm SAM-2nm	3.3	SAM on SiO <sub>2</sub> (Electrodes on top of CNTs)	10.1021/nl061534m (ref 8)
-10 to 10 (80 MV/m)	8	SiO <sub>2</sub> -100nm	SiO <sub>2</sub> =3.9	PMMA passivation on top of CNT (Electrodes on top of CNT)	10.1143/JJAP.45.5501 (ref 14)
-5 to 5 (5.55 MV/m)	0.5	ZrO <sub>2</sub> -90nm	ZrO <sub>2</sub> =10	PVDF-TrFE passivation on top of CNT (CNT film on top of electrodes)	10.1063/1.4895069 (ref 15)
-1.5 to 3 (10 MV/m)	0.3	TiO <sub>2</sub> -30nm	TiO <sub>2</sub> =22	TiO <sub>2</sub> top gate (Electrodes on top of CNT film)	10.1021/acsnano.7b01164 (ref 16)
-5 to 5 (0.263 MV/m)	0.1	h-BN-80nm SiO <sub>2</sub> - 300nm	h-BN = 3.29 h-BN+SiO <sub>2</sub> = 3.75	PTFE + h-BN (CNT on top of electrodes)	This work

**Table S1: Comparison of the hysteresis in this work to the literature**